

导热灌封胶 Thermal Potting



产品介绍

PRODUCT INTRODUCTION

对于一些发热元器件需要的不仅仅是导热，有时候还需要灌封树脂将器件封装起来。导热灌封胶不仅解决了散热问题，而且保护元件不受环境的损害。

For some heating components, we need not only heat dissipation, but also potting resin to encapsulate the components. The heat conduction potting material not only solves the problem of heat dissipation, but also protects the components from environmental damage.

产品特点

PRODUCT FEATURE

- 高导热, 低应力
- 适合多公差的使用场景
- 可自动化点胶
- Provide silicone and non-silicone products
- High insulation
- Suitable for high humidity and corrosive environment

典型应用

TYPICAL APPLICATION

- 同时提供含硅和非硅产品
- Provide silicone and non-silicone products
- 高绝缘性
- High insulation
- 适合高温、腐蚀环境
- Suitable for high humidity and corrosive environment
- 光伏逆变器, 接线盒
- Photovoltaic inverter, junction box
- 伺服和变频
- Servo and Frequency converter
- 电池包, 车载充电机, 充电桩
- Battery pack, OBC, Charging pile
- 继电器
- Relay
- 马达
- Motor

产品参数

PRODUCT PARAMETER

产品型号 Product Name	导热系数 Thermal Conductivity	密度 Density	混合粘度 Mixed Viscosity	操作时间 Pot Life	固化时间 Cure Time		体积电阻率 Volume Resistivity	使用温度 Application Temperature	阻燃等级 Flammability Rating	保质期 Shelf Life
	W/m.K	g/cm ³	cPs@10S ⁻¹	min@25°C	h@25°C	min@80°C	Ω·cm	°C	UL-94	month
SPO 30	3.0	3.00	10000	120	6	30	10 ¹³	-40 ~ 150	V-0	6
SPO 40	4.2	3.20	14000	120	6	30	10 ¹³	-40 ~ 150	V-0	6